



## **FQB17N08L / FQI17N08L**

### 80V LOGIC N-Channel MOSFET

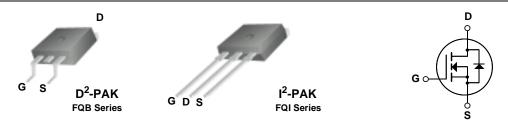
#### **General Description**

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology is especially tailored to minimize on-state resistance, provide superior switching performance, and withstand a high energy pulse in the avalanche and commutation modes. These devices are well suited for low voltage applications such as automotive, high efficiency switching for DC/DC converters, and DC motor control.

#### **Features**

- 16.5A, 80V,  $R_{DS(on)} = 0.1\Omega$  @ $V_{GS} = 10$  V
- Low gate charge (typical 8.8 nC)
- Low Crss (typical 29 pF)
- Fast switching
- 100% avalanche tested
- · Improved dv/dt capability
- 175°C maximum junction temperature rating
- Low level gate drive requirements allowing direct operation from logic drives



### **Absolute Maximum Ratings** T<sub>C</sub> = 25°C unless otherwise noted

Symbol	Parameter		FQB17N08L / FQI17N08L	Units
V <sub>DSS</sub>	Drain-Source Voltage		80	V
I <sub>D</sub>	Drain Current - Continuous (T <sub>C</sub> = 25°C	)	16.5	Α
	- Continuous (T <sub>C</sub> = 100°C	C)	11.6	А
I <sub>DM</sub>	Drain Current - Pulsed	(Note 1)	66	Α
V <sub>GSS</sub>	Gate-Source Voltage		± 20	V
E <sub>AS</sub>	Single Pulsed Avalanche Energy	(Note 2)	100	mJ
I <sub>AR</sub>	Avalanche Current	(Note 1)	16.5	Α
E <sub>AR</sub>	Repetitive Avalanche Energy	(Note 1)	6.5	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	6.5	V/ns
$P_{D}$	Power Dissipation (T <sub>A</sub> = 25°C) *		3.75	W
	Power Dissipation (T <sub>C</sub> = 25°C)		65	W
	- Derate above 25°C		0.43	W/°C
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range		-55 to +175	°C
T <sub>L</sub>	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300	°C

#### **Thermal Characteristics**

Symbol	Parameter	Тур	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		2.31	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient *		40	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		62.5	°C/W

<sup>\*</sup> When mounted on the minimum pad size recommended (PCB Mount)

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Cha	aracteristics					
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V, } I_{D} = 250 \mu\text{A}$	80			V
ΔBV <sub>DSS</sub> / ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	$I_D = 250 \mu\text{A}$ , Referenced to 25°	C	0.08		V/°C
I <sub>DSS</sub>	Zana Cata Valta na Busin Commant	V <sub>DS</sub> = 80 V, V <sub>GS</sub> = 0 V			1	μΑ
	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 64 V, T <sub>C</sub> = 150°C			10	μΑ
I <sub>GSSF</sub>	Gate-Body Leakage Current, Forward	V <sub>GS</sub> = 20 V, V <sub>DS</sub> = 0 V			100	nA
I <sub>GSSR</sub>	Gate-Body Leakage Current, Reverse	$V_{GS} = -20 \text{ V}, V_{DS} = 0 \text{ V}$			-100	nA
On Cha	aracteristics					
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	1.0		2.0	V
R <sub>DS(on)</sub>	\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\			0.076	0.100	
DO(011)	On-Resistance	$V_{GS} = 5 \text{ V}, I_D = 8.25 \text{ A}$		0.090	0.115	Ω
9 <sub>FS</sub>	Forward Transconductance	$V_{DS} = 25 \text{ V}, I_D = 8.25 \text{ A}$ (Note	4)	12.4		S
C <sub>iss</sub> C <sub>oss</sub> C <sub>rss</sub>	Input Capacitance Output Capacitance Reverse Transfer Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0  MHz		120 29	155 37	pF pF pF
C <sub>rss</sub>	Reverse Transfer Capacitance			29	37	pF
Switch	ing Characteristics					
	T 0 D 1 T					
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>22</sub> = 40 V I <sub>2</sub> = 16.5 A		7	25	ns
t <sub>d(on)</sub>	Turn-On Delay Time Turn-On Rise Time	$V_{DD} = 40 \text{ V}, I_{D} = 16.5 \text{ A},$ $R_{C} = 25 \Omega$		7 290	25 590	ns ns
	•	$R_G = 25 \Omega$				
t <sub>r</sub>	Turn-On Rise Time			290	590	ns
$t_{\rm r}$ $t_{\rm d(off)}$	Turn-On Rise Time Turn-Off Delay Time	$R_G = 25 \Omega$		290 20	590 50	ns ns
t <sub>r</sub> t <sub>d(off)</sub> t <sub>f</sub>	Turn-On Rise Time Turn-Off Delay Time Turn-Off Fall Time	$R_G=25~\Omega$ (Note 4	5)	290 20 75	590 50 160	ns ns ns
$\begin{array}{c} t_r \\ t_{d(off)} \\ t_f \\ Q_g \end{array}$	Turn-On Rise Time Turn-Off Delay Time Turn-Off Fall Time Total Gate Charge	$R_G = 25~\Omega$ (Note 4 $V_{DS} = 64~V,~I_D = 16.5~A,$	5)	290 20 75 8.8	590 50 160 11.5	ns ns ns
$\begin{array}{c} t_r \\ t_{d(off)} \\ t_f \\ Q_g \\ Q_{gs} \\ Q_{gd} \\ \end{array}$	Turn-On Rise Time Turn-Off Delay Time Turn-Off Fall Time Total Gate Charge Gate-Source Charge Gate-Drain Charge	$R_{G} = 25~\Omega \label{eq:controller}$ (Note 4) $V_{DS} = 64~V,~I_{D} = 16.5~A,$ $V_{GS} = 5~V \label{eq:controller}$ (Note 4)	5)	290 20 75 8.8 2.0	590 50 160 11.5	ns ns ns nC
$\begin{array}{c} t_r \\ t_{d(off)} \\ t_f \\ Q_g \\ Q_{gs} \\ Q_{gd} \\ \end{array}$	Turn-On Rise Time Turn-Off Delay Time Turn-Off Fall Time Total Gate Charge Gate-Source Charge Gate-Drain Charge	$R_G = 25~\Omega \label{eq:Note 4}$ (Note 4) $V_{DS} = 64~V,~I_D = 16.5~A,~V_{GS} = 5~V \label{eq:Note 4}$ (Note 4)	5)	290 20 75 8.8 2.0	590 50 160 11.5 	ns ns ns nC nC
$t_r$ $t_{d(off)}$ $t_f$ $Q_g$ $Q_{gs}$ $Q_{gd}$ Drain-S	Turn-On Rise Time Turn-Off Delay Time Turn-Off Fall Time Total Gate Charge Gate-Source Charge Gate-Drain Charge  Source Diode Characteristics and Maximum Continuous Drain-Source Diode	$R_G = 25 \Omega$ (Note 4) $V_{DS} = 64 \text{ V}, I_D = 16.5 \text{ A},$ $V_{GS} = 5 \text{ V}$ (Note 4) $V_{GS} = 5 \text{ V}$ (Note 4) $V_{GS} = 5 \text{ V}$ (Note 4) $V_{GS} = 5 \text{ V}$	5) 5)	290 20 75 8.8 2.0 5.4	590 50 160 11.5	ns ns ns nC
$\begin{array}{c} t_r \\ t_{d(off)} \\ t_f \\ Q_g \\ Q_{gs} \\ Q_{gd} \\ \\ \textbf{Drain-S} \\ I_{S} \\ \\ I_{SM} \end{array}$	Turn-On Rise Time Turn-Off Delay Time Turn-Off Fall Time Total Gate Charge Gate-Source Charge Gate-Drain Charge  Source Diode Characteristics at Maximum Continuous Drain-Source Diode Maximum Pulsed Drain-Source Diode F	$R_G = 25 \Omega$ (Note 4) $V_{DS} = 64 \text{ V}, I_D = 16.5 \text{ A}, V_{GS} = 5 \text{ V}$ (Note 4) (Note 4) $V_{CS} = 5 \text{ V}$ (Note 5) $V_{CS} = 5 \text{ V}$ (Note 5) $V_{CS} = 5 \text{ V}$ (Note 6) $V_{CS} = 5 \text{ V}$	5)	290 20 75 8.8 2.0 5.4	590 50 160 11.5   16.5 66	ns ns ns nC nC
$\begin{array}{c} t_r \\ t_{d(off)} \\ t_f \\ Q_g \\ Q_{gs} \\ Q_{gd} \\ \\ \textbf{Drain-S} \\ \textbf{I}_S \\ \end{array}$	Turn-On Rise Time Turn-Off Delay Time Turn-Off Fall Time Total Gate Charge Gate-Source Charge Gate-Drain Charge  Source Diode Characteristics and Maximum Continuous Drain-Source Diode	$R_G = 25 \Omega$ (Note 4) $V_{DS} = 64 \text{ V}, I_D = 16.5 \text{ A},$ $V_{GS} = 5 \text{ V}$ (Note 4) $V_{GS} = 5 \text{ V}$ (Note 4) $V_{GS} = 5 \text{ V}$ (Note 4) $V_{GS} = 5 \text{ V}$	5)	290 20 75 8.8 2.0 5.4	590 50 160 11.5 	ns ns ns nC nC

- $\label{eq:Notes:Notes:1} \begin{tabular}{ll} \textbf{Notes:} \\ \textbf{1. Repetitive Rating: Pulse width limited by maximum junction temperature} \\ \textbf{2. L} = \textbf{0.5mH, } I_{AS} = \textbf{16.5A, } V_{DD} = 25V, R_G = 25 \ \Omega, Starting \ T_J = 25^{\circ}C \\ \textbf{3. } I_{SD} \le \textbf{16.5A, } \text{ didt} \le 300A/\mu\text{s, } V_{DD} \le BV_{DSS,} \ Starting \ T_J = 25^{\circ}C \\ \textbf{4. } \text{ Pulse Test: Pulse width } \le 300\mu\text{s, Duty cycle} \le 2\% \\ \textbf{5. Essentially independent of operating temperature} \\ \end{tabular}$

## **Typical Characteristics**

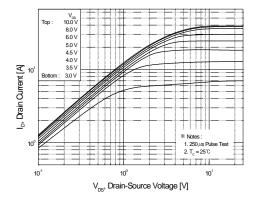


Figure 1. On-Region Characteristics

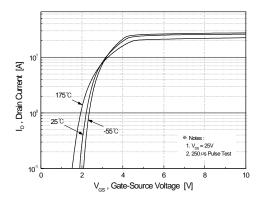


Figure 2. Transfer Characteristics

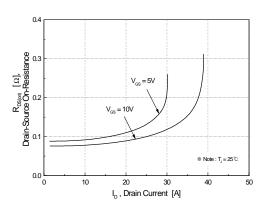


Figure 3. On-Resistance Variation vs.
Drain Current and Gate Voltage

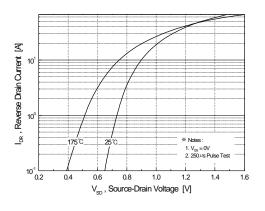


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

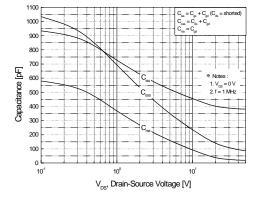


Figure 5. Capacitance Characteristics

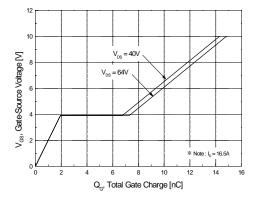
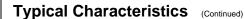
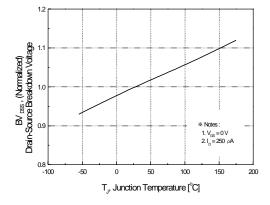


Figure 6. Gate Charge Characteristics

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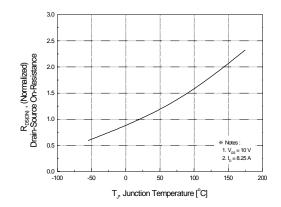
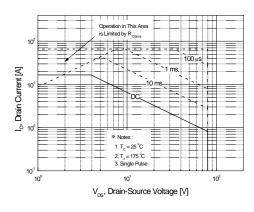


Figure 7. Breakdown Voltage Variation vs. Temperature

Figure 8. On-Resistance Variation vs. Temperature



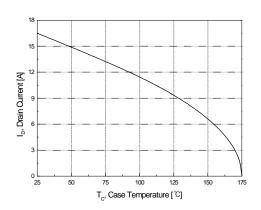


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

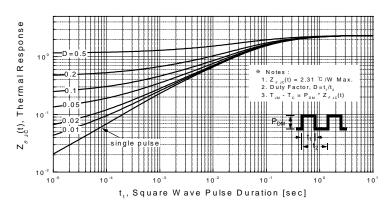
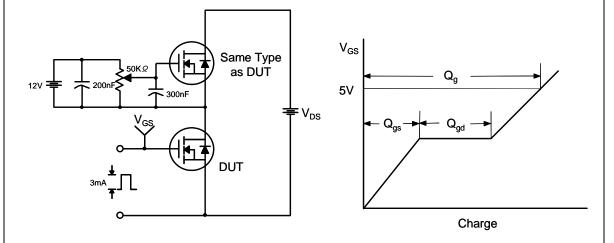


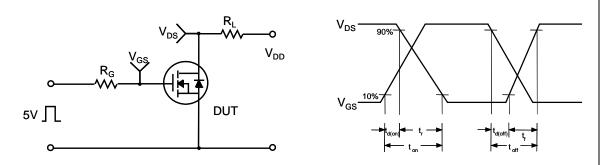
Figure 11. Transient Thermal Response Curve

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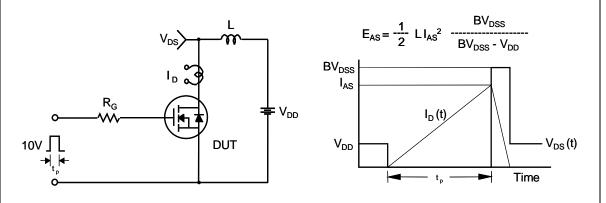
### **Gate Charge Test Circuit & Waveform**



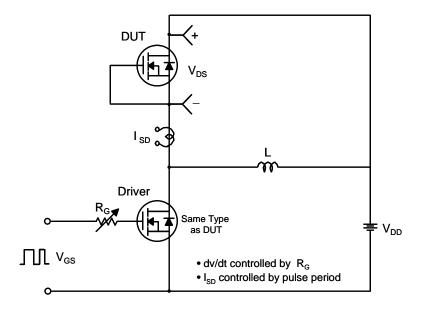
#### **Resistive Switching Test Circuit & Waveforms**

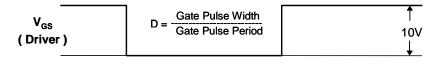


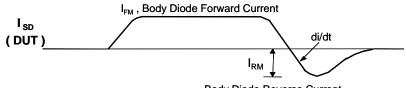
### **Unclamped Inductive Switching Test Circuit & Waveforms**



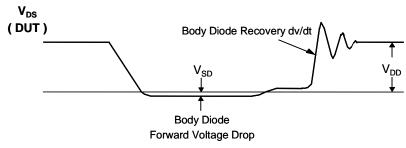
### Peak Diode Recovery dv/dt Test Circuit & Waveforms



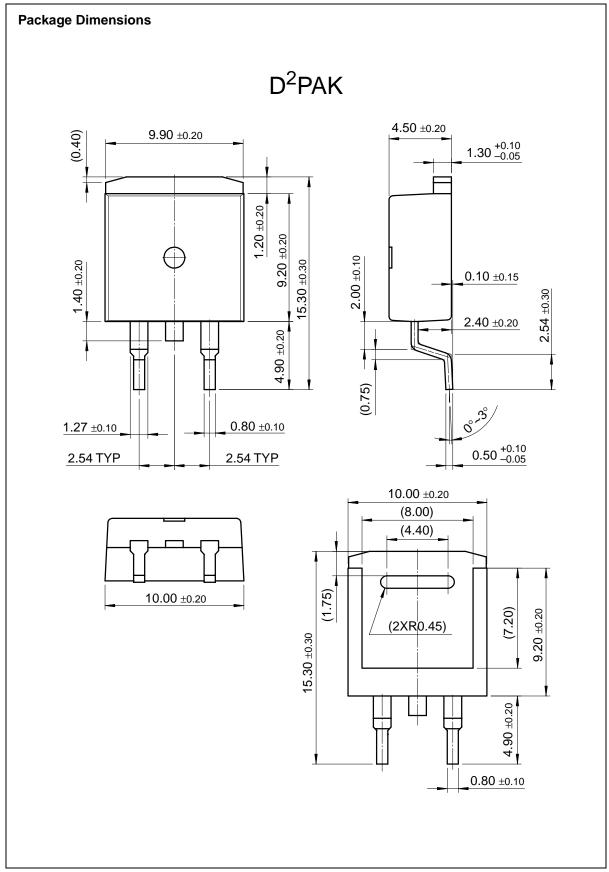


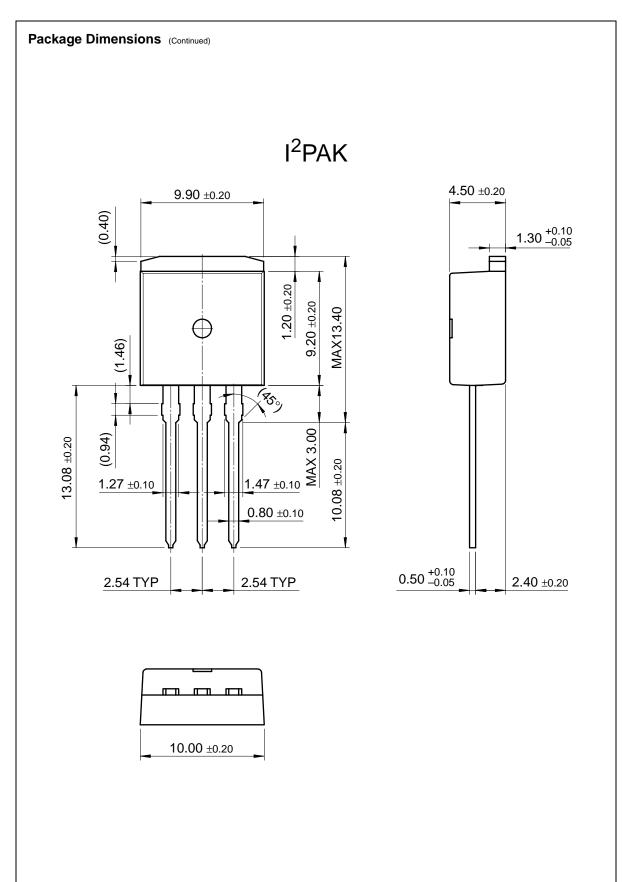






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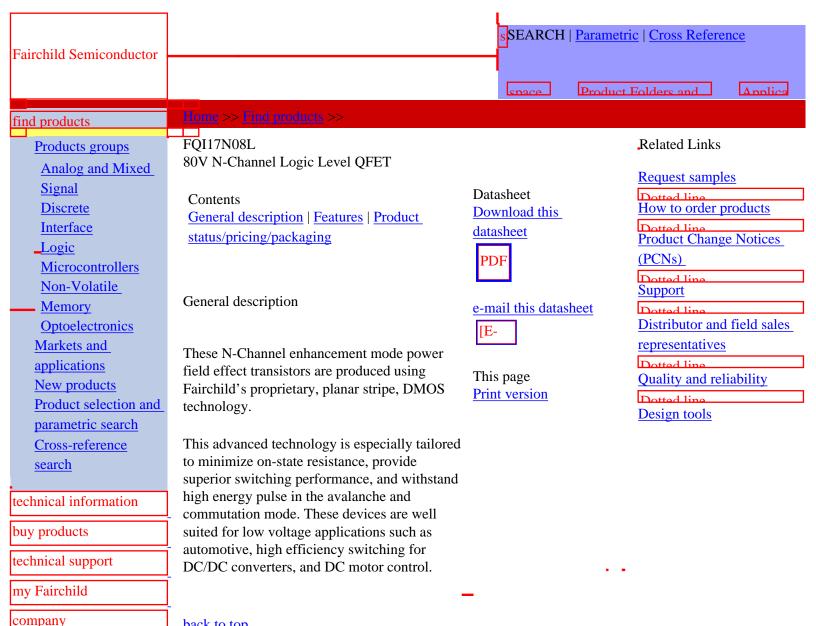
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#### PRODUCT STATUS DEFINITIONS

#### **Definition of Terms**

Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
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#### **Features**

- 16.5A, 80V,  $R_{DS(on)} = 0.1\Omega$  @ $V_{GS} = 10V$
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- Low Crss (typical 29pF)
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability
- 175°C maximum junction temperature rating
- Low level gate drive requirments allowing direct operation from logic drives

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### Product status/pricing/packaging

Product	Product status	Pricing*	Package type	Leads	Packing method
FQI17N08LTU	Full Production	\$0.54	TO-262(I2PAK)	3	RAIL

<sup>\* 1,000</sup> piece Budgetary Pricing

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# Features

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### Product status/pricing/packaging

Product	Product status	Pricing*	Package type	Leads	Packing method
FQB17N08LTM	Full Production	\$0.54	TO-263(D2PAK)	2	TAPE REEL

<sup>\* 1,000</sup> piece Budgetary Pricing

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### Models

Package & leads	Condition	Temperature range	Software version	Revision date
PSPICE				
TO-263(D2PAK)-2	Electrical	-55°C to 175°C	9.2	Oct 5, 2001

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